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A. APPENDIX:
PUBLICATION IN REFERRED AND PEER-REVIEWED
JOURNALS

S. N.	Publication
1	M. Singh, V. K. Rajendran, and J. C. Pandey, “A novel bisection method based algorithm to quantify interphase in epoxy alumina nanocomposites,” Computational Materials Science, vol. 183, p. 109912, Oct. 2020, doi: 10.1016/j.commatsci.2020.109912.
2	J. C. Pandey and M. Singh, “Evidences of interphase formation and concomitant change in the dielectric properties of epoxy-alumina nanocomposites,” Polymer Testing, vol. 91, p. 106802, Nov. 2020, doi: 10.1016/j.polymertesting.2020.106802.
3	J. C. Pandey and M. Singh, “Dielectric polymer nanocomposites: Past advances and future prospects in electrical insulation perspective,” SPE Polymers, Sep. 2021, doi: 10.1002/PLS2.10059.
4	M. Singh and J. C. Pandey, “Probing thermal conductivity of interphase in epoxy alumina nanocomposites,” Polymers & Polymer Composites. ‘Accepted’.